



Kulicke & Soffa Launches Katalyst™ — The Next Generation High Accuracy Flip Chip Bonde

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SINGAPORE--(BUSINESS WIRE)--Jul. 9, 2018-- Kulicke & Soffa Industries, Inc. (NASDAQ:KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today the launch of Katalyst™, the Company's leading edge high accuracy flip chip bonder. This new single platform addresses the industry's growing and changing application needs with its advanced bond head technology.

The Katalyst™ flip chip bonder expands the Company's advanced packaging portfolio by delivering solutions designed with a focus on:

- Highest **productivity** and yield with its unique bond head and flux dipping designs.
- Placement **accuracy and speed** with process control technology incorporating advanced alignment methods and post-place vision systems.
- **Advanced capabilities** with innovative software and hardware features such as process control monitoring that enables auto calibration; and host communication compatible with Automated Ground Vehicles (AGV), Over Head Transport (OHT), material tracking and standard factory interfaces.
- **Ease of use** with fully automated tool changers, calibration and teach procedures.

Shubneesh Batra, Kulicke & Soffa's Vice President of the Advanced Packaging Business Unit, said, "Katalyst™ is built on a brand new architecture, its advanced process control system and intuitive user interface address demanding production requirements. The intelligent design also delivers production flexibility, throughput and accuracy, adding significant value for current and next-generation flip chip applications."

"We are going to continue pushing the technology envelope in order to provide the best cost-of-ownership to our customers by designing and engineering products like the Katalyst™," added John Molnar, Vice President of Advanced Packaging Engineering at K&S.

Customer evaluations of the Katalyst™ flip chip bonder will commence in October 2018.

Please contact your local sales and services representative for more information on K&S' comprehensive solutions.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ:KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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